

SOLDERING AN ELECTRONICS PACKAGE TO A MOTHERBOARD

ABSTRACT

In some example embodiments, a method includes engaging a first contact on a motherboard with a second contact on an electronic package. A portion of one of the first and second contacts is covered with an interlayer that has a lower melting temperature than both of the first and second contacts. The method further includes bonding the first contact to the second contact by melting the interlayer to diffuse the interlayer into the first and second contacts. The bonded first and second contacts have a higher melting temperature than the interlayer before melting. In other example embodiments, an electronic assembly includes a motherboard having a first contact that is bonded to a second contact on an electronic package. An interlayer is diffused within the first and second contacts such that they have a higher melting temperature than the interlayer before the interlayer is diffused into the first and second contacts.

"Express Mail" mailing label number: EV 370239643 US

Date of Deposit: March 24, 2004

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